



Material Content Data Sheet



Sales Product Name		TLE6251DS		Issued		28. August 2013		
MA#		MA000977676						
Package		PG-DSO-8-16		Weight*		83.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.755	4.49	4.49	44922	44922
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8581	
wire	non noble metal	copper	7440-50-8	29.121	34.84	35.75	348414	357531
	noble metal	gold	7440-57-5	0.189	0.23	0.23	2261	2261
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1120
plastics	plastics	epoxy resin	-	4.306	5.15		51517	
	inorganic material	silicondioxide	60676-86-0	42.403	50.74	56.00	507323	559960
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9737	9737
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7780	7780
glue	plastics	acrylic resin	-	0.327	0.39		3918	
	noble metal	silver	7440-22-4	1.161	1.39	1.78	13891	17809
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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